

PRODUCT EVALUATION



Date: February, 2007

**PRODUCT EVALUATION REPORT FOR
Series:740/741/742/743/744/745/746
TIN WHISKER TEST**

**Tin Whisker Report for
Series: 740/741/742/743/744/745/746**

Resistor chip array testing performed per conditions as outlined in Table 1.

Test	Test Condition	Maximum Whisker Length
Temperature Cycling	-55°C to +125°C, 1000 Cycles	26µm SEM measurements
High Temperature / High Humidity Exposure	+85°C / 85% RH, 1000 Hours	9µm SEM measurements
Ambient Storage	6 Months	5µm SEM measurements

Table 1. Test Conditions and Results

CONSTRUCTION:

- 1 - Inner electrode Silver (Ag) Thick Film Conductive
- 2 - Inner plating: Nickel (Ni) plating 3-12µm
- 3 - Outer plating: Tin (Sn) plating 3-12µm

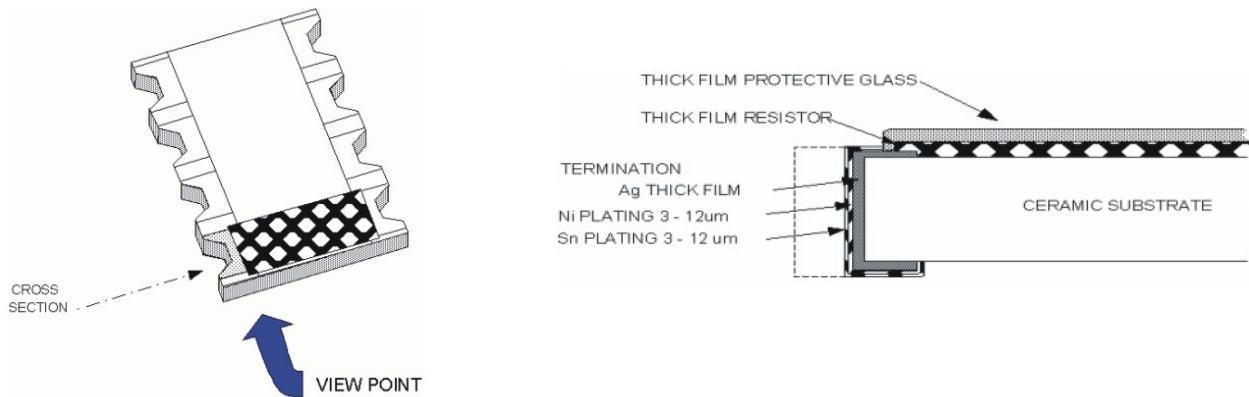


Figure 1. Construction Diagram

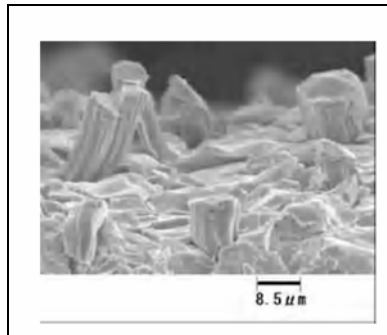


Figure 2. Tin Whisker growth after Temperature Cycling

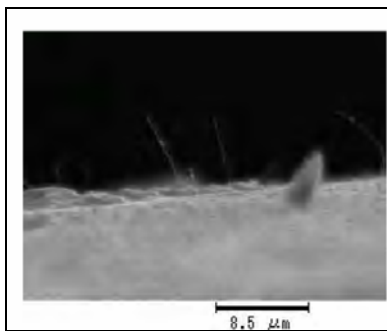


Figure 3. Tin Whisker growth after High Temperature and High Humidity

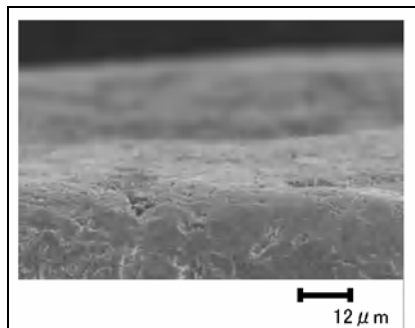


Figure 4. Tin Whisker growth after Ambient Storage

This test report data is for reference only, based on the conditions and samples used during the evaluation and is not guaranteed for all environments or all conditions.